

## TRANSMITTAL

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<b>Title of Invention</b>	<b>A LOW THERMAL BUDGET (MOL) LINER, A SEMICONDUCTOR DEVICE COMPRISING SAID LINER AND METHOD OF FORMING SAID SEMICONDUCTOR DEVICE</b>							
Application Number : Date : First Named Applicant:        Laura Brown Confirmation Number: Attorney Docket Number:       FIS920030370								
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<table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Todd M. C. Li Registered Number: 45554</td><td>Todd M. C. Li</td><td>Attorney</td></tr></table>			Submitted By:	Elec. Sign.	Sign. Capacity	Todd M. C. Li Registered Number: 45554	Todd M. C. Li	Attorney
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Documents being submitted:	Files
us-assignment	FIS920030370-usassn.xml us-assignment.xsl us-assignment.dtd FIS920030370assign1.tif FIS920030370assign2.tif FIS920030370amd1.tif FIS920030370amd2.tif
us-request	FIS920030370-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	FIS920030370-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	FIS920030370-usidst.xml us-ids.dtd us-ids.xsl
us-declaration	FIS920030370dec1.tif
us-declaration	FIS920030370dec2.tif
us-declaration	FIS920030370dec3.tif
application-body	FIS920030370-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd FIS920030370dwg1.tif FIS920030370dwg2.tif

**Comments**

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